

DESCRIPTION

OK TO ENTER: /G.H./

PHOTOSENSITIVE POLYMER COMPOSITION, METHOD OF PRODUCING
PATTERN AND ELECTRONIC PARTS

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TECHNICAL FIELD

[0001] The present invention relates to a photosensitive polymer composition, a method of producing a pattern and electronic parts using this composition. More particularly, the present invention relates to a positive type heat resistant photosensitive polymer composition which becomes a polybenzoxazole heat resistant polymer by heat treating and which is utilizable as a surface protection film and an interlayer insulating film in electronic parts such as semiconductor devices, and a method of producing a pattern, and electronic parts using this composition.

BACKGROUND ART

[0002] Conventionally, polyimide has been widely used as surface protection films or interlayer insulating films because of its advantages in resistance to heat, mechanical property and electric property, as well as easy film formability and planarizability of film surface.

[0003] When polyimide is used as the surface protection film or the interlayer insulating film, a forming process of through holes is performed by an etching process usually with the use of positive type photoresists. However, this forming process includes application and removal of the photoresists, and is therefore complicated. Thus, heat resistant materials having photosensitivity have been investigated for the purpose of streamlining works in this forming process.

[0004] Concerning photosensitive polyimide compositions, a